1. (Currently Amended) An electronic component, comprising:

a leadframe;

a platform;

an electronic member located on the platform and connected to the leadframe by electrical conductors; and

a housing which encloses the electronic member and the platform, where first and second support regions each comprising a lobe are provided on the platform on corresponding peripheral portions to support the platform during fabrication of the housing, where the housing has upper and lower support indentations formed therein that expose an upper surface and a lower surface, respectively, of an outer peripheral portion of each lobe to thereby allow each lobe to support the platform during fabrication of the housing, where at least a portion of the first and second support regions project beyond the housing subsequent to the fabrication of the housing.

2. (Cancelled)

3. (Cancelled)

4. (Cancelled)

5.(Previously Presented) The electronic component of claim 1, further comprising a transition zone located between the lobe and a remaining portion of the platform, where at least one notch-shaped depression is provided within the transition zone.

6. (Cancelled)

7. (Previously Presented) The electronic component of claim 1, where the leadframe comprises at least one connecting piece that protrudes from the housing, where the at least one connecting piece is connected to the electronic member.

8. (Previously Presented) The electronic component of claim 1, where the leadframe comprises a plurality of connecting pieces that each protrude from the housing, where each connecting piece is connected to the electronic member.

9. (Previously Presented) The electronic component of claim 1, where the leadframe comprises a metal alloy.

10. (Previously Presented) The electronic component of claim 1, where a thin anticorrosive film extends along at least a section of the lobe element.

11. (Previously Presented) The electronic component of claim 1, where at least a section of a surface of the leadframe is coated with a metal alloy.

12. (Cancelled)

13. (Previously Presented) The electronic component of claim 1, where the electronic member comprises a Hall effect sensing device.

14. (Cancelled)

15. (Cancelled)

16. (Cancelled)

17. (Previously Presented) A Hall effect sensing device, comprising:

a leadframe;

a platform;

a magnetic sensing element located on the platform and connected to the leadframe by electrical conductors; and

a housing which encloses the magnetic sensing element and at least a central portion of the platform, where first and second lobes are provided on opposite peripheral ends of the platform to support the platform during fabrication of the housing, where at least a portion of the first and second lobes project beyond the housing, and a first notch-shaped depression is located between the first lobe and the platform to provide a first moisture barrier, and a second notch-shaped depression is located between the second lobe and the platform to provide a second moisture barrier.

18. (Cancelled)

19. (Previously Presented) The Hall effect sensing device of claim 18, where a thin anticorrosive film extends along at least a section of the first lobe and along a section of the second lobe.

20. (Previously Presented) The Hall effect sensing device of claim 17, where the first and second lobes extend along the same axis.

21. (Currently Amended) A magnetic sensing device, comprising:

a leadframe;

a platform;

a semiconductor die comprising a magnetic sensing element located on the platform and connected to the leadframe by electrical conductors; and

a package that encloses the semiconductor die and at least a central portion of the platform, where first and second lobes are provided on opposite peripheral ends of the platform to support the platform during fabrication of the package, where the package has upper and lower support indentations formed therein that expose an upper surface and a lower surface, respectively, of an outer peripheral portion of each lobe to thereby allow each lobe to support the platform during fabrication of the package, where at least a portion of the first and second lobes project beyond the package.

22. (Previously Presented) The magnetic sensing device of claim 21, comprising a first notch-shaped depression located between the first lobe and the platform to provide a first moisture

barrier, and a second notch-shaped depression located between the second lobe and the platform to provide a second moisture barrier

23. (Previously Presented) The sensing device of claim 22, where a thin anticorrosive film extends along at least a section of the first lobe and along a section of the second lobe.

24. (Previously Presented) The sensing device of claim 23, where the first and second lobes extend along the same axis.

25. (Previously Presented) The sensing device of claim 24, where the semiconductor die comprises a Hall effect sensing element.

26. (Currently Amended) A magnetic sensing device, comprising:

a leadframe;

a platform;

a semiconductor die comprising a magnetic sensing element located on the platform and connected to the leadframe by electrical conductors; and

means for packaging the semiconductor die and at least a central portion of the platform, where first and second lobes are provided on opposite peripheral ends of the platform and extend along a common axis outside the means for packaging, where the means for packaging has upper and lower support indentations formed therein that expose an upper surface and a lower surface, respectively, of an outer peripheral portion of each lobe to thereby allow each lobe to support the platform during fabrication of the means for packaging.

27. (Previously Presented) The magnetic sensing device of claim 26, comprising a first notch-shaped depression located between the first lobe and the platform to provide a first moisture barrier, and a second notch-shaped depression located between the second lobe and the platform to provide a second moisture barrier.

28. (Previously Presented) The magnetic sensing device of claim 27, comprising a thin anticorrosive film extends along at least a section of the first lobe and along a section of the second lobe, where the first and second lobes extend along the same axis, and the semiconductor die comprises a Hall effect sensing element.